



Serial No.: 09/943,763

**VERSION OF SPECIFICATION WITH MARKINGS TO SHOW CHANGES MADE**

Please replace Paragraph [0007] as follows:

[0007] In forming a semiconductor device package, semiconductor dice are typically bonded to the paddles of the leadframe strip with an adhesive polymer, such as epoxy or a thermoplastic, with soft solder, or with a gold-silicon eutectic layer. Generally, each die mount paddle is slightly larger than the attached semiconductor die. The conductive bond pads of the semiconductor die are then wire bonded to the inner leads surrounding the semiconductor die, generally by the use of [the ]well-known thermocompression bonding [method]methods, but sometimes by thermosonic or ultrasonic bonding methods.

Please replace Paragraph [0017] as follows:

[0017] It is, therefore, an object of the invention to provide a semiconductor device wherein the frequency of wire bond failures and die-to-paddle bond failures is reduced, the frequency of required wire bond rework is reduced, and the manufacturing cost is reduced.

Please replace Paragraph [0018] as follows:

[0018] It has been generally assumed in the industry that the die mount paddle does not move during down-bonding of the semiconductor die[,] or during subsequent wire bonding. However, it has been discovered that significant movement sometimes may exist, and this movement contributes to poor semiconductor die-to-paddle bonding and can be a major cause of the observed failure, i.e., immediate "no-stick" or subsequent debonding of the wire bonds from the bond pads of the semiconductor die and/or from the metal inner leads.

Please replace Paragraph [0019] as follows:

[0019] In accordance with the invention, the pattern of paddle and leads on the leadframe is configured to provide a paddle with clampable tabs extending therefrom. The tabs extend outwardly from areas of the paddle which are otherwise largely unsupported or farthest

IN THE SPECIFICATION:

Please replace Paragraph [0007] as follows:

A1 [0007] In forming a semiconductor device package, semiconductor dice are typically bonded to the paddles of the leadframe strip with an adhesive polymer, such as epoxy or a thermoplastic, with soft solder, or with a gold-silicon eutectic layer. Generally, each die mount paddle is slightly larger than the attached semiconductor die. The conductive bond pads of the semiconductor die are then wire bonded to the inner leads surrounding the semiconductor die, generally by the use of well-known thermocompression bonding methods, but sometimes by thermosonic or ultrasonic bonding methods.

Please replace Paragraph [0017] as follows:

A2 [0017] It is, therefore, an object of the invention to provide a semiconductor device wherein the frequency of wire bond failures and die-to-paddle bond failures is reduced, the frequency of required wire bond rework is reduced, and the manufacturing cost is reduced.

Please replace Paragraph [0018] as follows:

A3 [0018] It has been generally assumed in the industry that the die mount paddle does not move during down-bonding of the semiconductor die or during subsequent wire bonding. However, it has been discovered that significant movement sometimes may exist, and this movement contributes to poor semiconductor die-to-paddle bonding and can be a major cause of the observed failure, i.e., immediate "no-stick" or subsequent debonding of the wire bonds from the bond pads of the semiconductor die and/or from the metal inner leads.

Please replace Paragraph [0019] as follows:

A4 [0019] In accordance with the invention, the pattern of paddle and leads on the leadframe is configured to provide a paddle with clampable tabs extending therefrom. The tabs extend outwardly from areas of the paddle which are otherwise largely unsupported or farthest from the paddle support bars. These tabs may be formed on the sides of the paddle along which